

## TECHNICAL CHARACTERISTICS

### 1. General Characteristics

Dimension: 13.56L x 13.38W x 1.60H mm

Weight: Approx. 0.35 g

Contact principle: Friction technology

Operating position: Shaft up / Down / Horizontal

Mounting System: SMT Type (without post)

Durability: 5,000 cycles min.

### 2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0

RoHS Directive 2011/65/EU Compliant

### 3. Electrical Characteristics

Number of contacts: 8 pins

Contact resistance: 100 mΩ / 20 mA

Insulation resistance: >1000 MΩ / 500 VDC

### 4. Solderability

Wave: Not applicable

IR reflow: 260°C, 10 sec. Max.

Manual soldering: 360°C, 3 sec. Max.

### 5. Environmental Characteristics

Operating temperature: - 25°C ~ + 85°C

Operating humidity: 10 % ~ 95 % RH

Storage temperature: - 40°C ~ + 85°C

Storage humidity: 10 % ~ 95 % RH

### 6. Pin Assignments

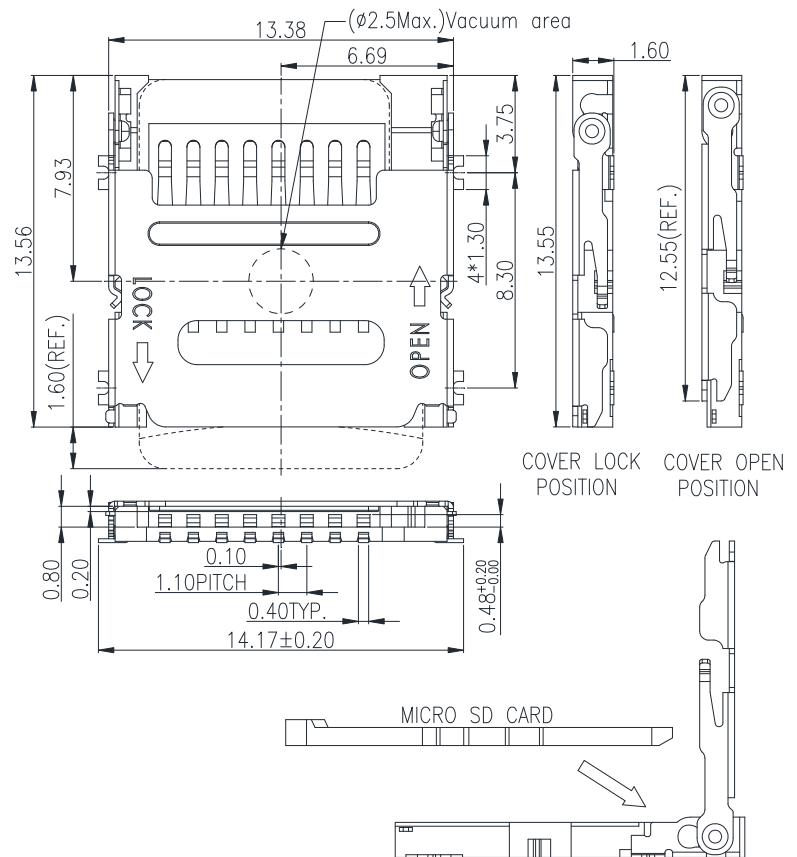
Pin	Micro SD Mode	
	Name	Description
1	DAT2	Data Line (Bit 2)
2	CD/DAT3	Card Detect / Data Line (Bit 3)
3	CMD	Command Response
4	VDD	Supply Voltage
5	CLK	Clock
6	VSS	Supply Voltage Ground
7	DAT0	Data Line (Bit 0)
8	DAT1	Data Line (Bit 1)

**H&V Micro SD Card Connector**

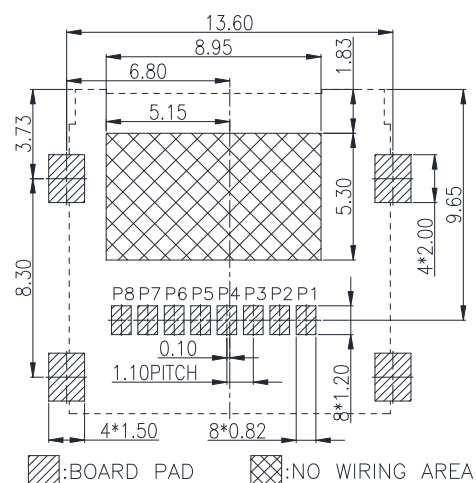
**Model No.: MCA-T01**

**Revision: 1.0**

**Date: SEP. 22, 2014**



Unit: mm; Tolerances: ±0.15 mm  
Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm  
Reference dimension for PCB layout

Note:

1. Coplanarity of solder pins 0.10mm max.

2. Recommended thickness of solder paste > 0.15mm.